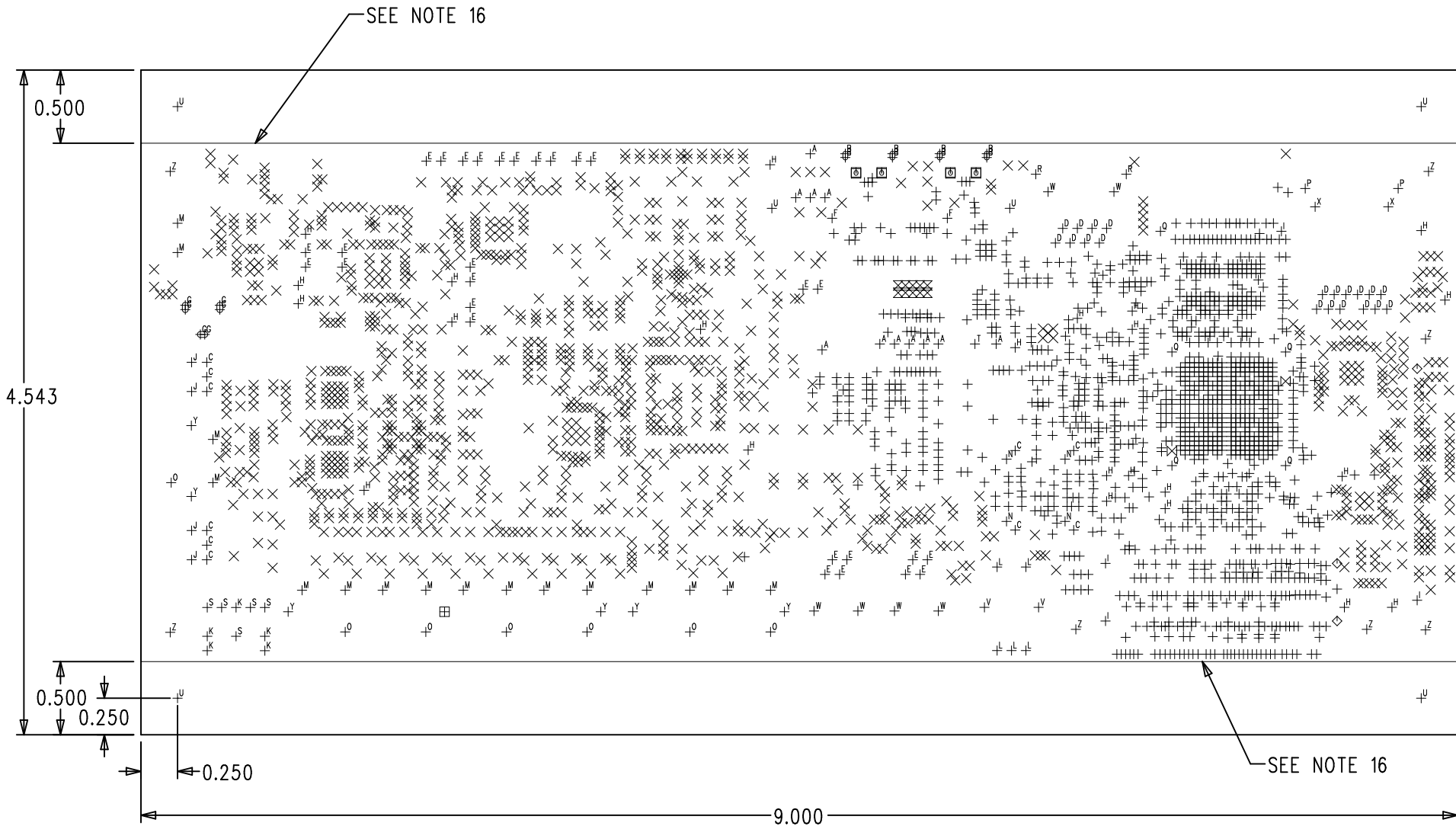
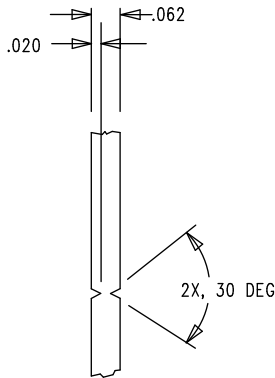
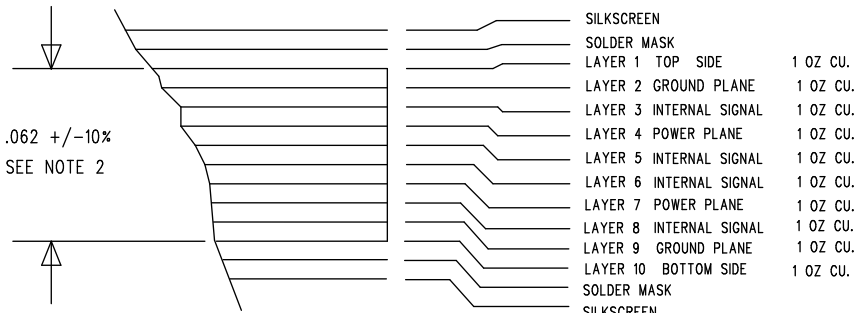


SIZE	QTY	SYM	PLATED	TOL
0.006	1456	+	YES	+0.000/-0.006
0.012	1299	×	YES	+/-0.003
0.026 x 0.033	4	□	YES	+/-0.003
0.028	3	◇	NO	+/-0.003
0.029	10	⊠	YES	+/-0.003
0.032	2	⊠	NO	+/-0.003
0.032	11	+ ^A	YES	+/-0.003
0.033 x 0.059	4	+ ^B	YES	+/-0.003
0.033	10	+ ^C	YES	+/-0.003
0.035	20	+ ^D	YES	+/-0.003
0.038	28	+ ^E	YES	+/-0.003
0.04	2	+ ^F	NO	+/-0.003
0.04 x 0.07	3	+ ^G	YES	+/-0.003
0.04	23	+ ^H	YES	+/-0.003
0.044	4	+ ^I	NO	+/-0.003
0.045	4	+ ^J	YES	+/-0.003
0.047	5	+ ^K	NO	+/-0.003
0.047	5	+ ^L	YES	+/-0.003
0.051	16	+ ^M	YES	+/-0.003
0.057	4	+ ^N	NO	+/-0.003
0.059	7	+ ^O	YES	+/-0.003
0.062	2	+ ^P	YES	+/-0.003
0.063	5	+ ^Q	NO	+/-0.003
0.063	2	+ ^R	YES	+/-0.003
0.071	5	+ ^S	YES	+/-0.003
0.089	1	+ ^T	NO	+/-0.003
0.125	6	+ ^U	NO	+/-0.005
0.125	2	+ ^V	YES	+/-0.005
0.128	6	+ ^W	NO	+/-0.005
0.138	2	+ ^X	NO	+/-0.005
0.14	6	+ ^Y	NO	+/-0.005
0.144	7	+ ^Z	NO	+/-0.005
0.187	1	⊞	NO	+/-0.005



10 LAYER CONSTRUCTION DETAIL
SCALE : NONE




SCORING DETAIL
2 PLACES

REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
0.1	NEW RELEASE	C.C.D.	10/19/15	
0.2	UPDATED PER ECO2016-003	C.C.D.	02/02/16	
1.0	UPDATED PER ECO2016-016	C.C.D.	05/10/16	
1.1	UPDATED PER ECO2017-011	C.C.D.	03/02/17	
1.2	UPDATED PER ECO2017-0xx	C.C.D.	04/18/17	
1.2	UPDATED PER ECO2017-018	C.C.D.	10/13/17	
1.3	UPDATED PER ECO2018-006	C.C.D.	05/15/18	

UNLESS OTHERWISE SPECIFIED

- BOARD TO BE FABRICATED PER IPC-6012 (LATEST REVISION) CLASS 2.
- MATERIAL: FR-370HR OR EQUIVALENT, THICKNESS: .062 +/-10%.
VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
- PLATING: SEE CONSTRUCTION DETAIL FOR FINISHED COPPER WEIGHT.
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE
PER IPC-6012 (LATEST REVISION) WITH AMENDMENT 1, CLASS 2
REQUIREMENTS. WITH NO SINGLE MEASUREMENT LESS THAN 0.00071
IN THE PLATED HOLES.
- FINISH: SURFACES TO BE COATED BY ENIG OF 3 TO 5 MICROINCHES OVER
A MINIMUM OF 150-200 MICROINCHES OF LOW STRESS NICKEL.
- SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES
PER GERBER FILES. VENDOR MAY ADJUST SOLDERMASK
PAD SIZE AS NEEDED.
- SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
- ARTWORK: MINIMUM FEATURE SIZE = 0.005
MINIMUM AIR GAP = 0.004
- ALL DIMENSIONS ARE IN INCHES.
- CONTROLLED IMPEDANCE (+/-10%):
ALL .005" TRACES TO BE 50 OHM SINGLE ENDED.
ALL .0056" TRACES TO BE 50 OHM SINGLE ENDED.
ALL .0045" TRACES TO BE 100 OHM DIFFERENTIAL PAIRS.
ALL .0035" TRACES TO BE 100 OHM DIFFERENTIAL PAIRS.
- NON-FUNCTIONAL COPPER THIEVING IS ALLOWED ON OPEN AREAS.
- VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.
METHOD 1 IS PREFERRED.
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER
ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK.
AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO
VIA APERTURES BOTH SIDES.

METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/
IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES
THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES.
THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
- VIA HOLES (.006 & .012) REQUIRE TANGENCY ONLY, INSTEAD
OF ANNULAR RING.
- TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
- REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 3, 5, 6, AND 8 IS
ACCEPTABLE.
- USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
- V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.
- BUILD AS 1-UP PCB.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		 2 Elizabeth Drive Chelmsford, MA 01824	
	APPROVALS	DATE		
MATERIAL SEE NOTES	DRAWN C.C.D.	05/15/18	FABRICATION DRAWING ADSP-SC573 EZ-KIT	
	CHECKED			
FINISH SEE NOTES	ENGINEERING		SIZE B	REV. 1.3
	QUALITY		DWG. NO. A0760-2015	
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE 1 : 1	SHEET 1 OF 1